

# **MANOs**

Micro- & Nano-scale Optical Components Key Components for Novel Optical Devices and Systems





## **Application**

- Optical communications
- Spectroscopy
- Sensor technology
- Measuring technique
- Medicine
- Lasers
- Bio-technology
- Materials processing
- Imaging

#### **Specifications**

• wafer size: from 1 inch up to 5 inches

circular or square

• feature size: from x mm to nano-scale (>50 nm)

• structure depth: from x nm up to 8 μm

• aspect ratio: from 1 up to 6

profile: binary, multi-level, continuous

• wavelength: from DUV to IR

#### **Materials**

- Quartz-glass
- Silica (SiO<sub>3</sub>)
- Silicon (Si)
- Silicon-Nitride (Si<sub>3</sub>N<sub>4</sub>)
- Resins
- PMMA

### Fabrication technique

Advanced fabrication facilities:

- Photolithography (SÜSS-Maskaligners)
- Direct ebeam-writing (LEICA EBPG5000+) combined with
- Dry etching techniques (RIE & CAIBE)

#### Quality

- high fidelity pattern transfer
- high uniformity
- smooth surfaces
- steep sidewalls
- high optical efficiences
- low SNR



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